

What is claimed is:

1. An LTCC structure comprising:

a plurality of stacked layers of ceramic material including metallization in predetermined patterns on and through said layers;

said stacked layers including a plurality of exposed electrical conductors to which leads are to be bonded;

said conductors being of a metal which includes one or more additives to promote adhesion to said ceramic layer on which said conductors are deposited;

a bonding metal layer on top of said conductors at predetermined locations and being of said same metal as said conductors, however devoid of said one or more additives;

said leads being bonded to said bonding metal layer.

2. Apparatus according to claim 1 wherein:

said bonding metal layer is deposited on a limited area of a said conductor only where said lead is to be bonded.

3. Apparatus according to claim 1 wherein:

said conductors are of a gold paste with said additives;

said bonding metal layer is of a pure gold paste devoid of said additives.

4. Apparatus according to claim 1 wherein:

predetermined ones of said layers include respective cavities;

predetermined ones of said conductors being located on at least one said layer below the top layer of said stacked layers;

said predetermined ones of said conductors being accessible through said cavities for bonding of said leads.

5. A method of making an LTCC structure, comprising the steps of:

providing a plurality of ceramic layers to be stacked together to form a module;

applying to said layers, prior to said stacking, conductor patterns of a metal containing one or more additives to promote adhesion of said conductor patterns to said layers;

applying to areas of exposed conductors to which leads will be bonded said same metal, however devoid of said additives, to form a bonding layer at said areas;

stacking and firing said layers to form said module;

bonding said leads to said bonding layers on said exposed conductors.

6. A method according to claim 5 which includes:

providing predetermined ones of said layers with cavities such that some of said exposed conductors are on a layer other than a surface layer, and are accessible through said cavities for lead bonding.

7. A method of making an LTCC structure, comprising the steps of:

providing a plurality of ceramic layers to be stacked together to form a module;

applying to said layers, prior to said stacking, conductor patterns of a metal containing one or more additives to promote adhesion of said conductor patterns to said layers;

stacking and firing said layers to form said module;

applying to areas of conductors, on a surface layer, to which leads will be bonded, said same metal, however devoid of said additives, to form a bonding layer at said areas;

firing said stack a second time;

bonding said leads to said bonding layers.